



**Hampford Research INC**  
Handcrafted Solutions For A High-Tech World

## **BIS HEMA PHOSPHATE- TECH GRADE**

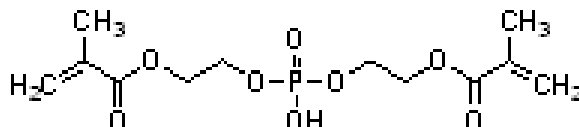
### **FP code 5049**

#### **General**

Bis HEMA phosphate is a unique liquid monomer designed to promote adhesion in industrial applications. It can be combined with acrylic resins, unsaturated polyesters and other UV curable resins.

For optimum performance, Bis HEMA phosphate is normally used between 1-5% by weight.

#### **Chemical structure**



#### **Product information**

PRODUCT TYPE:	Monomer/adhesion promoter
PRODUCT NAME:	Bis HEMA phosphate
TRADE NAMES:	Bis [2-(methacryloyloxy) ethyl] phosphate
CAS NO.	32435-46-4
APPLICATIONS:	Coatings
REGISTRATIONS:	TSCA, AICS, DSL, EINECS, ENCS, ECL
SHELF LIFE:	6 months when stored indoors at 25 (+/- 5) deg C

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### Typical properties

APPEARANCE:	Clear to yellow liquid
MOLECULAR WEIGHT	245 (average)
REFRACTIVE INDEX	1.4687
DENSITY @ 25°C	1.26
ACID VALUE (AVE)	270
MEHQ, INHIBITOR, PPM	500

**Packaging:** 1000g container

### Safety and Handling

This material should be handled in accordance with good industrial practice. Detailed information is provided in the SDS.

For additional information visit our website [www.hampfordresearch.com](http://www.hampfordresearch.com).

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